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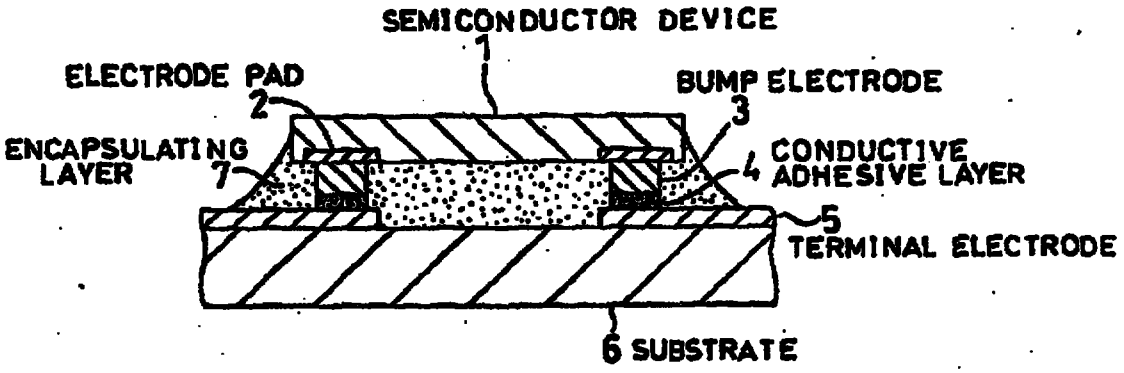
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(54) Title: SEMICONDUCTOR UNIT PACKAGE, SEMICONDUCTOR UNIT PACKAGING METHOD, AND ENCAPSULANT FOR USE IN SEMICONDUCTOR UNIT PACKAGING



(57) Abstract

An improved semiconductor unit package is disclosed. This package is implemented by a semiconductor device (1) having an electrode pad (2), a substrate (6) having a terminal electrode (5), a bump electrode (3) formed on the electrode pad (2), a conductive adhesion layer (4) with flexibility, and an encapsulating layer (7) formed by curing a composition the viscosity and thixotropy index of which are below 100 Pa·s and below 1.1, respectively. Such a composition essentially consists of (A) a resin binder that contains, for example, a polyepoxide, an acid anhydride, and a rheology modifier and (B) a filler. The rheology modifier is one capable of impeding interaction between a free acid contained in the acid anhydride and a polar group at the surface of the filler. An encapsulant with improved flowability is used, so that the encapsulant readily flows and spreads to fill a gap between the semiconductor device (1) and the substrate (6) with no air bubbles. This achieves semiconductor unit packages with high reliability and productivity.